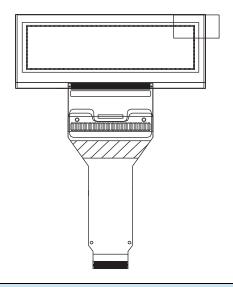


Vishay

COMPLIANT

132 x 32 Graphic OLED



FEATURES

· Type: graphic

• Display format: 132 x 32 dots

• Built-in controller: SSD1305

• Duty cycle: 1/32 • +3 V power supply

• Interface: 6800, 8080, serial, and I²C

With polarizer

• Material categorization: for definitions of compliance

please see www.vishay.com/doc?99912

MECHANICAL DATA						
ITEM	STANDARD VALUE	UNIT				
Module dimension	62.64 x 25.44 x 2.05 (max.)					
Viewing area	58.21 x 17.13					
Active area	55.41 x 15.33	mm				
Dot size	0.39 x 0.45	mm				
Dot pitch	0.42 x 0.48					
Mounting hole	n/a					

ABSOLUTE MAXIMUM RATINGS							
ITEM	CVMDOL	STANDAF	RD VALUE	UNIT			
I I EIVI	SYMBOL MIN.		MAX.	UNIT			
Supply voltage for logic (1)(2)	V_{DD}	-0.3	4	V			
Supply voltage for display (1)(2)	V_{CC}	0	15	v			
Operating temperature	T _{OP}	-40	+80	°C			
Storage temperature	T _{STG}	-40	+80	C			

Notes

- (1) All the above voltages are on the basis of " $V_{SS} = 0 V$ ".
- (2) When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

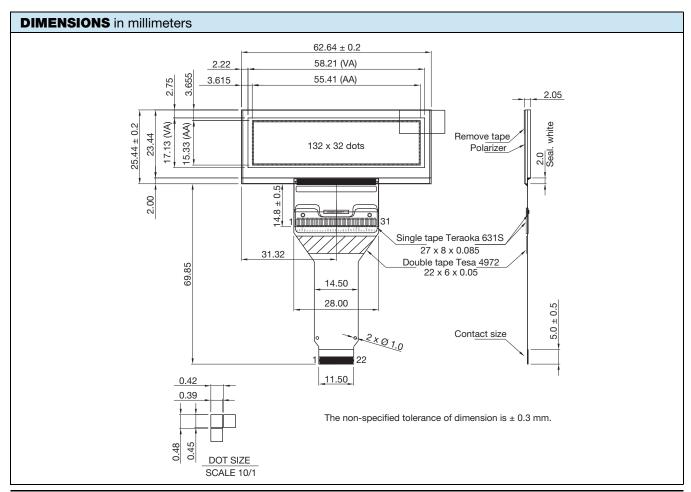
ELECTRICAL CHARACTERISTICS								
ITEM			ST	STANDARD VALUE				
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT		
Supply voltage for logic	V_{DD}	-	2.8	3.0	3.3			
Supply voltage for display	V _{CC}	-	10	12	15			
Input high voltage	V _{IH}	=	0.8 V _{DD}	-	V_{DD}	V		
Input low voltage	V _{IL}	-	0	-	0.2 V _{DD}	T v		
Output high voltage	V _{OH}	=	0.9 V _{DD}	=	V_{DD}			
Output low voltage	V _{OL}	=	0	-	0.1 V _{DD}	1		
50 % check board operating current	Icc	V _{CC} = 12 V	26	28	32	mA		

OPTIONS	3								
EMITTING COLOR				MOQ					
YELLOW	GREEN	RED	BLUE	WHITE	YELLOW	GREEN	RED	BLUE	WHITE
Yes	-	-	-	-	Yes	-	-	-	-

Revision: 12-Oct-16 Document Number: 37954

Vishay

INTERFA	INTERFACE PIN FUNCTION							
PIN NO.	SYMBOL		FUNCTION					
1	V _{CC}	Power supply for an	alog circuit.					
2	V _{COMH}	COM voltage output	. A capacitor should	be connected betwee	en this pin and V _{SS} .			
3	I _{REF}	Reference current in	put pin. A resistor ne	eds to be connected	between this pin and	d V _{SS} .		
4 to 11	D7 to D0	Data bus.						
12	E/RD#	Data read operation	is initiated when it is	pull low.				
13	R/W#	Data write operation	is initiated when it is	pull low.				
14	D / C#	Pull high for write / re	Data / command control. Pull high for write / read display data. Pull low for write command or read status.					
15	RES#	Reset signal input. V	Vhen it is low, initializ	ation of SSD1305 is e	executed.			
16	CS#	Chip select input.						
17	BS2	Communicating prot These pins are MCU		nput. See the following	g table:			
			68XX parallel	80XX parallel	Serial	I ² C		
		BS1	0	1	0	1		
18	BS1	BS2	BS2 1 1 0 0					
19	V_{DD}	Power supply for log	jic circuit.					
20	NC	No connection.						
21	V _{SS}	Ground.	Ground.					
22	V _{SS}	Ground.						



Revision: 12-Oct-16 2 Document Number: 37954



Vishay

1.Module Classification Information

 OLED
 132
 Y
 032
 B
 L
 P
 P
 3
 N
 0
 0
 000

 1
 2
 3
 4
 5
 6
 7
 8
 9
 10
 11
 12
 13

1	Brand : Vishay Inter	technology, Inc.						
2	Horizontal Format: 132 columns							
3	Display Type : N→Character Type, H→Graphic Type , Y→Tab Type ,O→COG Type							
4	Vertical Format: 32 Lines							
5	Serials code: B							
		A : Amber	R: RED					
	O.	B: Blue	C : Full color					
6	Emitting Color	G: Green	W: White					
		Y: Yellow Green	L: Yellow					
7	Polarizer	P: With Polarizer; N: Without Po	larizer					
8	Display Mode	P: Passive Matrix; A: Active Ma	trix					
9	Driver Voltage	3: 3.0 V; 5: 5.0V						
10	Touch Panel	N : Without touch panel; T: With touch panel						
		0 : Standard type						
		Sunlight Readable type						
11	Products type	2. Transparent OLED (TOLED)						
		3. Flexible OLED						
		4. OLED for Lighting						
		product grades:						
		0 : Standard(A-level)						
12	Product grades	2 : B-level						
12	Froduct grades	3 : C-level						
		4 : high class(AA-level)						
		5 : Customer offerings						
13	Serial No.	Application serial number(000~ZZZ)						



Vishay

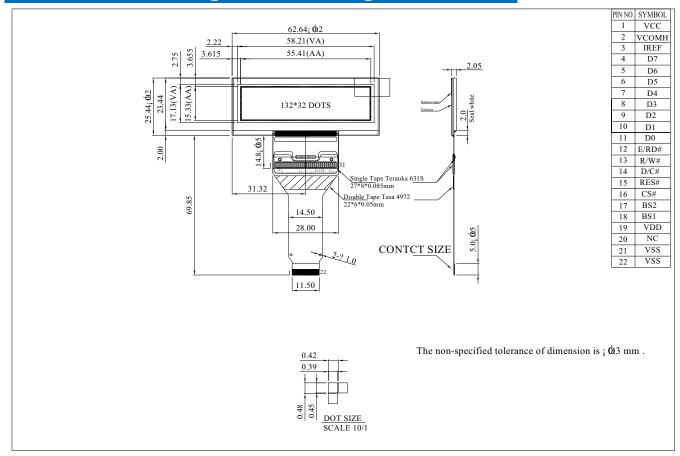
2.General Specification

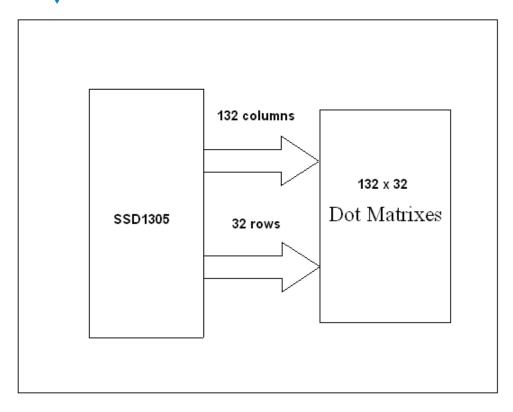
Item	Dimension	Unit
Dot Matrix	132 x 32	_
Module dimension	62.64 × 25.44 × 2.05 (mm)	mm
Active Area	55.41 × 15.33 (mm)	mm
Pixel Size	0.39 × 0.45 (mm)	mm
Pixel Pitch	0.42 × 0.48 (mm)	mm
Display Mode	Passive Matrix	
Display Color	Monochrome (Yellow)	
Drive Duty	1/32 Duty	



Vishay

3. Counter Drawing & Block Diagram







Vishay

4. Interface Pin Function

No.	Symbol	unction			
1	VCC	Power supply for analog circuit.			
2	VCOMH	Com Voltage Output. A capacitor should be connected petween this pin and VSS.			
3	IREF	Reference current input pin. A resistor should be connected between this pin and VSS.			
4~11	D7~D0	Data bus.			
12	E/RD#	Data read operation is initiated when it's pull low.			
13	R/W#	Data write operation is initiated when it's pull low.			
14	D/C#	Data/ Command control. Pull high for write/read display data. Pull low for write command or read status.			
15	RES#	Reset signal input. When it's low, initialization of SSD1305 is executed.			
16	CS#	Chip select input.			
17	BS2	Communicating Protocol Select These pins are MCU interface selection input. See the following table: 68XX-parallel 80XX-parallel Serial I2C			
18	BS1	BS1 0 1 0 1 BS2 1 1 0 0			
19	VDD	Power supply for logic circuit.			
20	NC	No connection			
21	VSS	Ground.			
22	VSS	Ground.			



Vishay

5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



Vishay

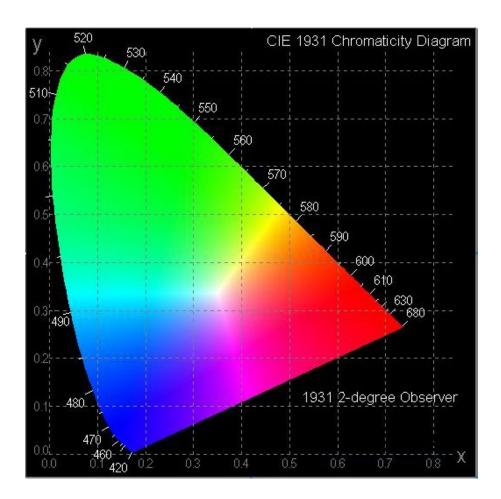
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	10	12	15	V
High Level Input	VIH	_	0.8×VDD	_	VDD	V
Low Level Input	VIL	_	0	_	0.2×VDD	V
High Level Output	VOH	_	0.9×VDD	_	VDD	V
Low Level Input	VOL	_	0	_	0.1×VDD	V
50% Check Board operatir Current	ng	VCC =12V	26	28	32	mA

Vishay

7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160			deg
View Angle	(Η)φ		160			deg
Contrast Ratio	CR	Dark	2000:1		_	_
Response Time	T rise	_		10		μs
response rime	T fall	_		10		μs
Display with 50% check Board Brightness			100	120		cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	





Vishay

8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	80,000 Hrs	100,000 Hrs	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

Vishay

9. Reliability

Content of Reliability Test

Environmenta	Il Test	T	Amulianki		
Test Item	Content of Test	Test Condition	Applicable Standard		
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80□ 240hrs			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80□ 240hrs			
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40□ 240hrs			
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60□,90%RH 240hrs			
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40 25 80 30min 5min 30min 1 cycle	-40□/80□ 100 cycles			
Mechanical Test					
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr			
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction			
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs			
Others					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time			

^{***} Supply voltage for OLED system =Operating voltage at 25°C

OLED-132Y032B-LPP3N00000



www.vishay.com

Vishay

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



Vishay

10.Inspection specification

NO	Item	Criterion		AQL			
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.		0.65			
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 		2.5			
03	OLED black spots, white spots, contamina tion (non-displ ay)	3.1 Round type following drawin Φ=(x+y)/2			SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2	2.5
		3.2 Line type : (A	As following Length $$ L \leq 3.0 L \leq 2.5 $$	Wi W: 0.0	awing) dth ≤0.02 02 < W ≤ 0.03 03 < W ≤ 0.05 05 < W	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible judge using black specifications, n to find, must che specify direction	k spot ot easy eck in	Ф: 0.2 0.8	ze Φ ≤0.20 20 < Φ≤0.50 50 < Φ≤1.00 00 < Φ tal Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
		Symbols Define: x: Chip length k: Seal width L: Electrode pad leng	t: Glass thickness a	Chip thickness : OLED side length	
		6.1 General glass ch 6.1.1 Chip on panel s	ip : surface and crack bet	ween panels:	
				THE PROPERTY OF THE PROPERTY O	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
	glass	1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td>2.5</td></z≦2t<>	Not exceed 1/3k	x≦1/8a	2.5
 ⊙ If there are 2 or more chips, x is total length of each chip 6.1.2 Corner crack: 		igth of each chip.			
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
1/2t < z ≤ 2t Not exceed 1/3k x		x≦1/8a			
⊙ If there are 2 or more chips, x is the total length of each ch			I length of each chip.		



Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t	NO	Item	Criterion	AQL			
k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t 6.2.2 Non-conductive portion: Glass crack y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤t OIf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. OIf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length	110	110111		TIQL			
L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t 6.2.2 Non-conductive portion: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t y: Chip width x: Chip length z: Chip thickness y≤L x≤1/8a 0 < z≤t o If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. o If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length x: lengt							
6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : y: Chip width x: Chip length z: Chip thickness y ≤ 0.5mm x ≤ 1/8a 0 < z ≤ t 6.2.2 Non-conductive portion:			1				
Glass crack y: Chip width x: Chip length z: Chip thickness y ≤ 0.5mm x ≤ 1/8a 0 < z ≤ t x ≤ 1/8a x ≤ 1/8a 0 < z ≤ t x ≤ 1/8a x ≤ 1/8							
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			يا عسب				
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			330				
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			The state of the s				
Glass crack y: Chip width			y: Chip width x: Chip length z: Chip thickness				
Glass crack y							
y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length			6.2.2 Non-conductive portion:				
y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length	06		***************************************	2.5			
y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length		crack	V ↑Z Y Y				
y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
thickness y ≤ L olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width thickness 0 < z ≤ t olf the ITO must remain and be inspected according to electrode terminal specifications. y: width x: length			<u> </u>				
y ≤ L x ≤ 1/8a 0 < z ≤ t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
 ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length 							
must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
 ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length 			1				
mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length			'				
6.2.3 Substrate protuberance and internal crack. y: width x: length			<u> </u>				
y: width x: length							
			Υ				
y							
y y y			y= 1102 X = U				
			y y y				
			÷€*				





NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65





NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65
I			



Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel

Vishay

11.Precautions in use of OLED Modules

Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3)Don't disassemble the OLED display module.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist OLED display module.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8)It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9)Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10)Supplier has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11)Supplier has the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Vishay has the right to modify the version.)

11.1. Handling Precautions

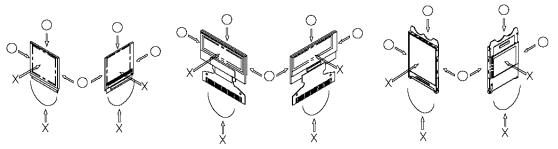
- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent
 - Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts.
 - These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



Vishay



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2. Storage Precautions

(1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.

(We recommend you to store these modules in the packaged state when they were shipped from Vishay Intertechnology Inc.

At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.

(2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.

OLED-132Y032B-LPP3N00000



www.vishay.com

Vishay

- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
- * Connection (contact) to any other potential than the above may lead to rupture of the IC.11.4.

Precautions when disposing of the OLED display modules

1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

11.5. Other Precautions

- (1) When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.
- Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
- (2) To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules.
- * Pins and electrodes
- * Pattern layouts such as the TCP & FPC
- (3) With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur.
- * Design the product and installation method so that the OLED driver may be shielded from light in actual usage.
- * Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes.
- (4) Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- (5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (6)Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.
- (7)Our company will has the right to upgrade and modify the product function.

Legal Disclaimer Notice



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

© 2017 VISHAY INTERTECHNOLOGY, INC. ALL RIGHTS RESERVED